

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	0	(light adj emitting adj diode) and encapsulate and protect\$4 and (heat adj treat) and humidity	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 09:08
2	BRS	L2	155	(light adj emitting adj diode) and encapsulate and protect\$4	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 07:52
3	BRS	L3	61	2 and heat	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 07:50
4	BRS	L4	28	3 and (humid\$4 moisture)	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 07:50
5	BRS	L5	269	(light adj emitting adj diode) and resin and cure	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 08:16
6	BRS	L6	250	5 and @ay<2000	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 07:54

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BRS	L7	159	(light adj emitting adj diode) and resin and harden	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 08:43
8	BRS	L8	1161	257/98.ccls. and @ay<2000	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 08:58
9	BRS	L9	43	8 and (epoxy adj resin) and (heat cure harden\$4)	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 08:55
10	BRS	L10	225	257/95.ccls. and @ay<2000	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 08:58
11	BRS	L11	336	(light adj emitting adj diode) and (protect\$4 adj film) and @ay<2000	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 09:19
12	BRS	L12	336	11 and @ay<2000	USPAT; EPO; JPO; DERWEN T; IBM_TD B	2002/07/10 09:20